Dexerials

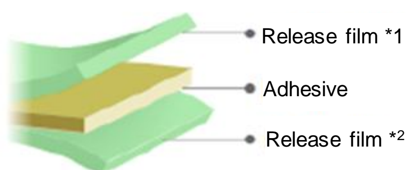
Technical Data Sheet

Thermosetting tapes for FPC D3430P

Features

- ■ Excellent heat resistant for solder reflow process after moisture absorption.
- ■ Excellent peeling strength for Polyimide, Glass Epoxy, Aluminum and Stainless Steel plate.
- ■ It is possible to store at room temperature.
- ■ Initial tack enables tentative positioning.

Structure



Product name	D3430P
Main component	Acryl / Epoxy
Carrier	Non-carrier
Color	Light yellow
Adhesive thickness (μm)	About 35
Release film *1 thickness (μm)	About 38
Release film *2 thickness (μm)	About 38
Bonding strength (N/10mm) ※	25
St'd size (width & length)	500mm × 100m

※90° peeling strength (substrate : Polyimide)

<Standard bonding condition>

■Vacuum quick press and post cure process

Press temperature : 180 to 190℃
Pressing time : 1 to 3min.
Vacuum time : 10 to 30 sec.
Pressure : 1.5 to 2.0MPa
Post cure condition : 160℃, 120min.

■Long press process

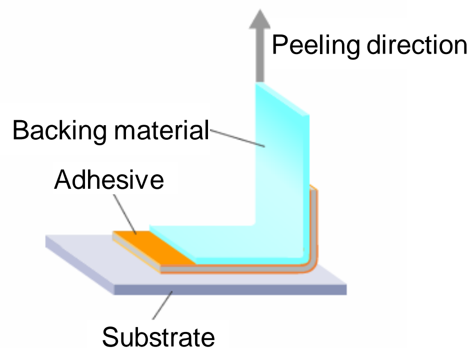
Press temperature : 160℃
Pressing time : 60min.
Pressure : 3.0MPa

Suitable use

■ Ideal for bonding FPC stiffener (Polyimide, Glass Epoxy, Aluminum, Stainless steel) that under go heat treatment such as solder reflow

Technical data

1. Bonding strength on various type of substrate (90° peeling)



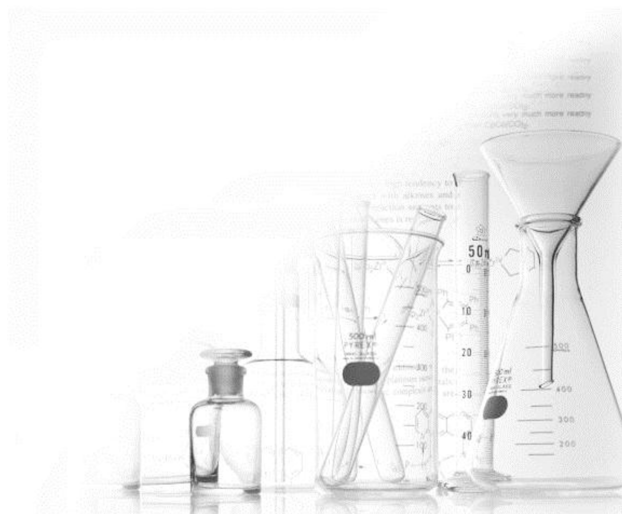
<90° peeling strength test>

<Test piece condition>
Substrate: Glass Epoxy/Polyimide/Aluminum/Stainless steel
Tape width: 10mm
Bonding condition: Standard processes
Measuring condition: 23℃±5℃ 60%±20%RH
Peeling speed: 50mm/min
Backing material: CCL (Copper Clad Laminate)
[Left at RT for one hour before measurement]

<Results>

(N/10mm)

		D3430P
Vacuum quick press and post cure	Polyimide	23
	Glass Epoxy	16
	Stainless steel	23
	Aluminum	14
Long press	Polyimide	25
	Glass Epoxy	16
	Stainless steel	25
	Aluminum	20



2. Solder reflow process heat resistance

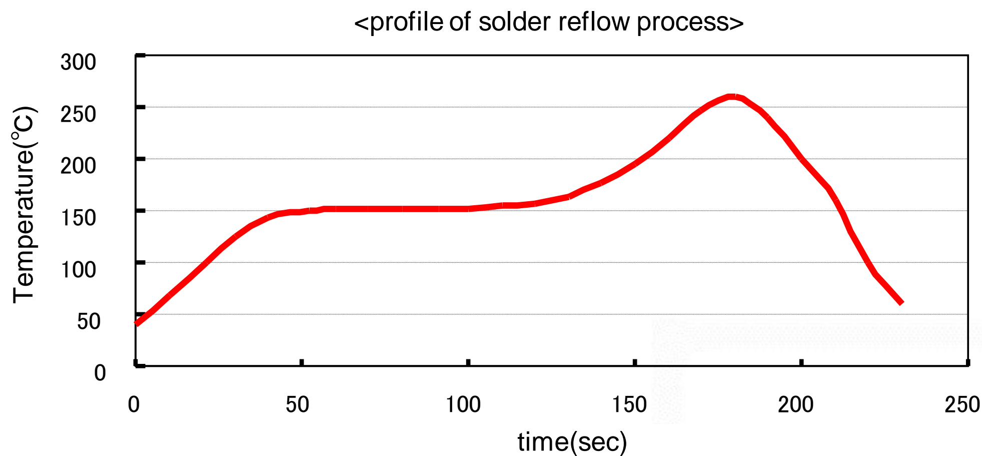
＜Test piece condition＞
Substrate: Polyimide film/ D3430P / CCL
Bonding condition: standard bonding condition
Solder reflow condition: Top 260℃
(Reference profile)
Measuring condition: 23℃±5℃ 60%±20%RH

＜Results＞ ＊Appearance after solder reflow process

Bonding condition	Treatment before reflow	Condition	D3430P
Vacuum quick press and post cure	Dry	1/100/-	No change
	Moisture absorption	96/40/90	No change
Long press	Dry	1/100/-	No change
	Moisture absorption	96/40/90	No change

※process time (h) / temperature(℃) / humidity (%)

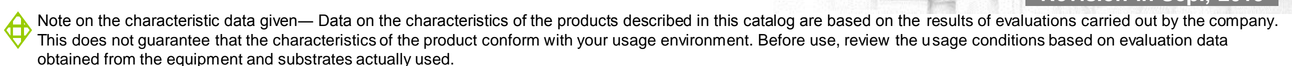
<profile of solder reflow process>



Notes

- Resin flow characteristics in D3430P series is greatly dependent on thickness, size and shapes of stiffeners. Please check the flowing before using. Especially, in the case of using the stiffeners with holes it is necessary to be careful.

Revision in Sep., 2013


Note on the characteristic data given— Data on the characteristics of the products described in this catalog are based on the results of evaluations carried out by the company. This does not guarantee that the characteristics of the product conform with your usage environment. Before use, review the usage conditions based on evaluation data obtained from the equipment and substrates actually used.

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